

80mA Low Noise LDO Voltage Regulator with Enable Function

DESCRIPTION

TS5213 is an efficient linear voltage regulator with ultra-low noise output, very low dropout voltage (typically 50mV at light loads and 320mV at 80mA), and very low ground current (225uA at 20mA), providing high output current even when the application requires very low dropout voltage. The Chip Enable (EN) includes a CMOS or TTL compatible input allows the output to be turned off to prolong battery life. When shutdown, power consumption drops nearly to zero. TS5213 is included a precision voltage reference, error correction circuit, a current limited output driver, over temperature shutdown and revered battery protection.

FEATURES

- Ultra Low Noise Output
- Output Current up to 80mA
- Low Power Consumption
- "Zero" Off-mode Consumption
- Logic Controlled Electronic Enable
- Current Limit & Thermal Shutdown Protection
- RoHS Compliant
- Halogen-Free according to IEC 61249-2-21

APPLICATION

- Cellular Telephones
- Palmtops, Notebook Computers
- Battery Powered Equipment
- SMPS Post Regulator and DC to DC Modules
- High-efficiency Linear Power Supplies
- Portable Application







SOT-25

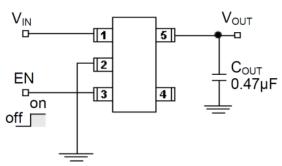


Pin Definition:

- 1. Input
- 2. Ground
- 3. Enable
- 4. N/C
- 5. Output

Notes: MSL 1 (Moisture Sensitivity Level) per J-STD-020

TYPICAL APPLICATION CIRCUIT



1

EN may be connected to VIN pin to regulation ON CIN > $0.1\mu F$ in basic operating COUT > $0.47\mu F$ in low noise operating



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) (Note 1)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Input Supply Voltage	V _{IN}	-20~ +20	V			
Enable Input Voltage	Vce	-20~ +20	V			
Power Dissipation (Note 2)	P _D	Internal limited				
Junction to Ambient Thermal Resistance	R _{ÐJA}	220	°C/W			
Operating Junction Temperature Range	ΓJ	-40 ~ +125	°C			
Storage Temperature Range	T _{STG}	-65 ~ +150	°C			
Lead Soldering Temperature (260°C)		5	S			

RECOMMEND OPERATING RATING (Note 2)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Input Supply Voltage	Vin	+2.5 ~ +16	V		
Enable Input Voltage	V _{CE}	0 ~ V _{IN}	V		

ELECTRICAL SPECIFICATIONS							
(V _{IN} = Vo+1V, Io = 100μA, C _{OUT} = 1uF, Vce ≥ 2V, T _A = 25°C unless otherwise noted)							
PARAMETER	CONDITIONS		MIN	TYP	MAX	UNIT	
O to AVAII o	V _{IN} = Vo + 1V		-3		3	%	
Output Voltage	-40°C ≤ T _J ≤ +125°C		-4		4		
Output Voltage Temp. Coefficient	(Note 5)			50	200	ppm/°C	
Line Regulation	$Vo+1V \leq V_{IN}$	≤ 16V		0.008	0.3	%	
Load Regulation (Note 6)	0.1mA ≤ lo ≤ 80mA			0.08	0.3	%	
Dropout Voltage (Note 7)	I _O = 100μA			50		mV	
	I _O = 20mA			230	300		
	I _O = 50mA			280	370		
	I _O = 80mA			320	420		
Quiescent Current	V _{EN} ≤ 0.4V (shutdown)			0.01	10	μA	
Ground Pin Current (Note 8)		$I_0 = 100 \mu A$		80			
	V _{EN} ≥ 2V	$I_0 = 20 \text{mA}$		225	750		
	(active)	$I_0 = 50 \text{mA}$		850		– μA –	
		$I_0 = 80 \text{mA}$		1800	3000		
Output Current Limit	Vout =0V			250	500	mA	
Power Supply Rejection Ratio	At f=100Hz, Io=100μA,			65		dB	
Thermal Regulation (Note 9)				0.05		%/W	

2



ENABLE FUNCTION					
(V _{IN} = Vo+1V, Io = 100μA, C _{OUT} = 1uF, Vce ≥ 2V, T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Enable Input Logic-Low Voltage	Regulation shutdown		1	0.6	V
Enable Input Logic-High Voltage	Regulation enable	2.0			V
Enable Input Current	V _{IL} ≤ 0.6V		0.01	1	μA
	V _{IH} ≥ 2.0V		15	50	V

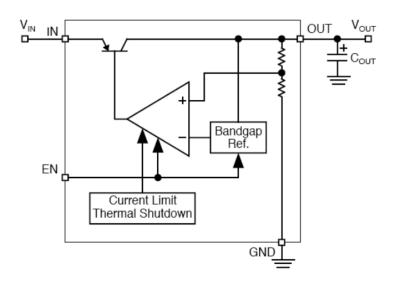
Note:

- 1. Exceeding the absolute maximum rating may damage the device.
- 2. The maximum allowable power dissipation at any Ta is $Pd(max) = [T_J(MAX) T_A] + \Theta_{JA}$. Exceeding the maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown.
- 3. Devices are ESD sensitive. Handling precautions recommended.
- 4. The device is not guaranteed to function outside its operating rating.
- 5. Output voltage temperature coefficient is defined as the worst-case voltage change divided by the total temperature range.
- Regulation is measured at constant junction temperature using low duty cycle pulse testing. Parts are tested for load regulation in the load range from 1mA to 80mA. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- 7. Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at 1V differential.
- 8. Ground pin current is the regulator quiescent current plus pass transistor base current. The total current drawn from the supply is the sum of the load current plus the ground pin current.
- 9. Thermal regulation is defined as the change in output voltage at a time "t" after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a 80mA load pulse at V_{IH} =16V for t=10ms.

ORDERING INFORMATION

OUTPUT VOLTAGE	ORDERING CODE	PACKAGE	PACKING
3.3V	TS5213CX533 RFG	SOT-25	3,000pcs / 7" Reel
5V	TS5213CX550 RFG	SOT-25	3,000pcs / 7" Reel

BLOCK DIAGRAM



3



APPLICATION INFORMATION

Enable Input

TS5213 series feature an active-high (>2V) enable (EN) input that allows ON/OFF control of the regulator. Current drain reduces to "zero" when the device is shutdown, with only micro-amperes of leakage current. The EN is compatible with CMOS logic interfacing. EN may be directly tied to V_{IH} and pulled up to the maximum supply voltage.

Input Capacitor Requirement

An input capacitor of 0.17µF or greater is recommended when the device is more than 10" away from the bulk AC supply capacitance or when the supply is a battery.

Output Capacitor Requirement

The TS5213 series requires an output capacitor to maintain stability and improve transient response is necessary. The TS5213 is ultra-stable, requiring only 0.47µF of output capacitance for stability. It is stable with all type of capacitors, including the tiny, low-ESR ceramic chip capacitors. The output capacitor value may be increased without limit.

No Load Stability

The TS5213 series will remain stable and in regulation with no load, unlike many other voltage regulators. This is especially important in CMOS RAM keep alive applications.

Thermal Characteristics

TS5213 series is designed to provide 80mA of continuous current in a very small package. Maximum power dissipation can be calculated based on the output current and the voltage drop across the part. To determine the maximum power dissipation of the package, use the junction-ambient thermal resistance of the device and the following basic equation:

$$P_{D(MAX)} = [T_{J(MAX)} - T_A]/\Theta_{JA}$$

 $T_{J(MAX)}$ is the maximum junction temperature of the die(125°C), and Ta is the ambient operating temperature. Θ_{JA} is layout dependent, the actual power dissipation of the regulator circuit can be determined using the equation:

$$P_D = (V_{IN} - V_{OUT}) * I_{OUT} + V_{IN} * I_{GND}$$

Substituting Pd(max) for Pd and solving for the operating conditions that are critical to the application will give the maximum operating conditions for the regulator circuit. For example, when operating the TS5213CX550 at room temperature with a minimum footprint layout, the maximum input voltage for a set output current can be determined as follows:

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P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / 220^{\circ}C/W

P_{D(MAX)} = 455mW
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The junction to ambient thermal resistance for the minimum footprint is 220°C/W, the maximum power dissipation must not be exceeded for proper operation. Using the output voltage of 5.0V and an output current of 80mA, the maximum input voltage can be determined. Form the electrical characteristics table, the maximum ground current for 80mA output current is 1mA.

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445mW = (V_{IN} - 5.0V) * 80mA + V_{IN} * 1.8mA 445mW = V_{IN} * 80mA - 5.0 * 80mA + V_{IN} * 1.8mA 445mW = V_{IN} * 80mA - 400mW + V_{IN} * 1.8mA 845mW = V_{IN} * 81.8mA V_{IN} (max) = 10.33V
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Therefore, a 5.0V application at 80mA of output current can accept a maximum input voltage of 10.33V in a SOT-25 package.

4



ELECTRICAL CHARACTERISTICS CURVE

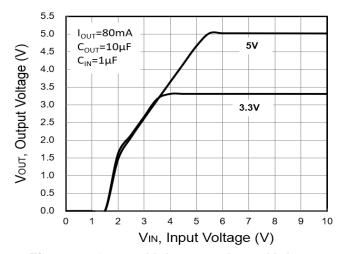


Figure 1. Output Voltage vs. Input Voltage

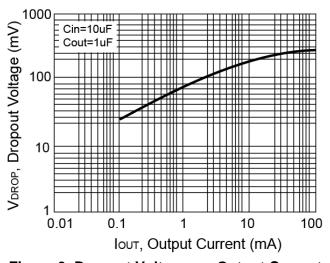


Figure 3. Dropout Voltage vs. Output Current

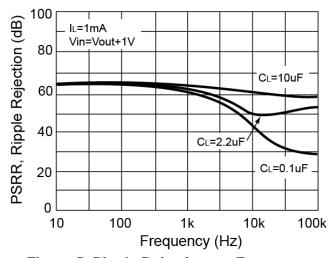


Figure 5. Ripple Rejection vs. Frequency

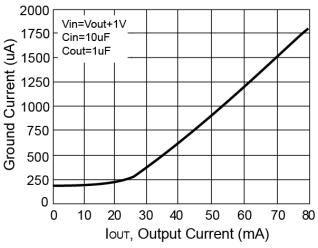


Figure 2. Ground Current vs. Output Current

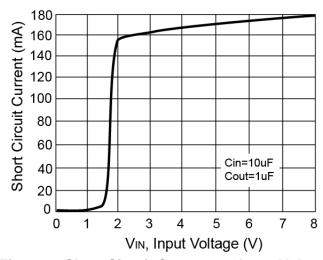


Figure 4. Short Circuit Current vs. Input Voltage

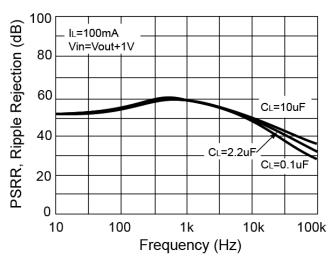
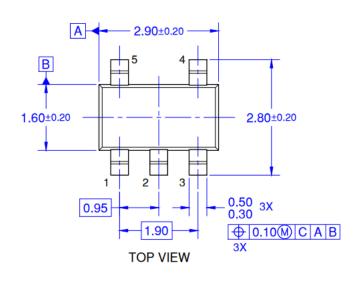


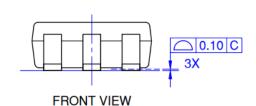
Figure 6. Ripple Rejection vs. Frequency

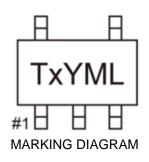


PACKAGE OUTLINE DIMENSIONS

SOT-25







T = Device code

X = Voltage code (5=5V, S=3.3V)

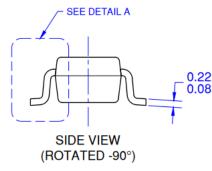
Y = Year code

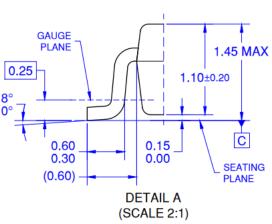
M = Month Code for Halogen Free Product

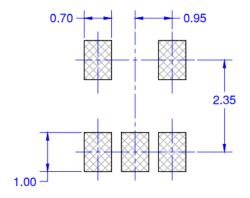
O =Jan P =Feb Q =Mar R =Apr S =May T =Jun U =Jul V =Aug

W =Sep X =Oct Y =Nov Z =Dec

L = Lot code (1~9, A~Z)







SUGGESTED PAD LAYOUT

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC MO-178, VARIATION AA.
- 4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DWG NO REF: HQ2SD07-026 REV A.

6